Product Informat

### **Product Features**

- High dynamic range downconverter with integrated LO, IF, & RF amps
- RF: 1900 2200 MHz
- IF: 150 300 MHz
- +38 dBm Output IP3
- +21 dBm Output P1dB
- 5 dB Noise Figure
- Single supply operation (+5 V)
- Pb-free 6mm 28-pin QFN package
- Low-side LO configuration
- Common footprint with other PCS/UMTS/cellular versions

### **Product Description**

The CV111-2 is a high linearity downconverter designed to meet the demanding issues for performance, functionality, and cost goals of current and next generation mobile infrastructure basestations It provides high dynamic range performance in a low profile Pb-free surface-mount leadless package that measures 6 x 6 mm square.

Functionality includes RF amplification, frequency conversion and IF amplification, while as integrated LO driver amplifier powers the passive mixer. MCM is implemented with reliable and mature gaAs MESFET and InGaP HBT technology

applications include / conversion, modulation and demodulation for recei used in CDMA, CDMA2000, W-CDMA / IMZ200 GPRS and EDGE mobile infrastructure technologic for UMTS frequency bands.

# **Functional Diag** IF Amp 20 GND 18 GND LO Driver Amp 16 GND 15 LO IN

Top View

## Specifications (1)

•		$/ \sim 1$	/	2 Y	
Parameters	Units	(Min)	TO	Max	Comments
RF Frequency Range	MHz		1900 - 1200		
LO Frequency Range	MHz		1600 2050		
IF Center Frequency Range	M/Hz_/		300 B		See note 2
% Bandwidth around IF center frequency	/%	$\sim 1$	V10₹7.5		See note 3
IF Test Frequency	MHz		$\cup_{240}$		
SSB Conversion Gain	dB /		⇒ 21		Temp = $25^{\circ}$ C
Gain Drift over Temp (-40° C to 85° C)	dB√	(27)	±1.0		Referenced to +25° C
Output IP3	<b>√</b> dBm	(5,7	+38		See note 4
Output IP2	<b>d</b> Bm/		+48		See note 4
Output 1dB Compression Point	dBm		+21		
Noise Figure	√dB ∕		5.0		See note 5
LO Input Drive Level	\dBm\	2.5	0	+2.5	
LO-RF Isolation / (	dB	$\triangleright$	45		$P_{LO} = 0 \text{ dBm}$
LO-IF Isolation	(AB)		35		$P_{LO} = 0 \text{ dBm}$
Return Loss: RF Port	(dB/		14		
Return Loss: LO Port	<i>/</i> ∞33))		14		
Return Loss: IF Port	∠ gB		14		
Operating Supply Voltage	?{{\substack} v	+4.9	+5	+5.1	
Supply Current	$\bigcup_{mA}$	290	360	480	
FIT Rating	Milures/1E9 hrs			72.1	@ 70° C ambient, 90% confidence
Junction Temperature	°C			160	See note 6

circuit (shown on page 3) with a low side LO = 0 dBm in a downconverting application over the operating case temperature range Specifications when using the application specific

#### The maximum junction te es a minimum MTBF rating of 1 million hours of usage

### Absolute(Maximum Rating

Parart (0)	Rating	
Operating Case Temperature	-40° to +85° C	
Storage Temperature	-55° to +125° C	
DC (VOLLEGE)	+6 V	
Innerion Temperature	+220 °C	
RF Input (continuous)	+2 dBm	

Operation of this device above any of these parameters may cause permanent damage

### **Ordering Information**

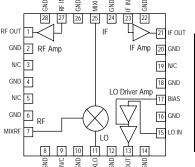
Part No.	Description
CV111-2	UMTS-band Dual-Branch Downconverter (leaded OFN Pkg)
CV111-2F	UMTS-band Dual-Branch Downconverter (lead-free/RoHS-compliant OFN Pkg)
CV111-2PCB240	Fully-Assembled Application Board, IF = 240MHz

Specifications and information are subject to change without notice

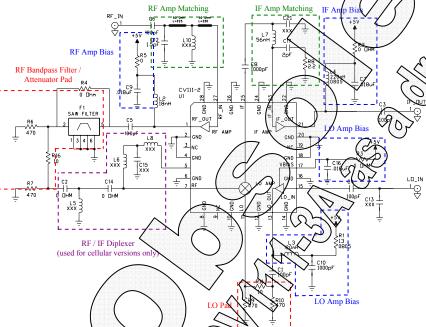
IF matching components affect the court is requency. Proper component values for other IF center frequencies than shown can be provided by emailing to applications engineering@wj.com. The IF bandwidth of the converter is leftice as 159 abound any center frequency in its operating IF frequency range. The bandwidth is determined with external components. Specifications are valid around the total  $\pm 7.5\%$  bandwidth. is with a court frequency of 200 MHz, the specifications are valid from  $200 \pm 15$  MHz. Assumes the supply voltage = 5% OIP3 is measured with  $\Delta f = 1$  MHz with IF  $_{out} = 5$  dBm / tone. Assumes LO injection noise is filtered at the thermal noise floor, -174 dBm/Hz, at the RF, IF, and Image frequencies.

**Product Information** 

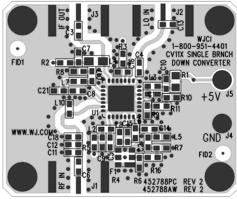
### **Device Architecture / Application Circuit Information**



Typical Downconverter Performance Chain Analysis									
		Outnut	Outnut			Cumulative)Performance			
Stage	Gain (dB)	Output P1dB (dBm)	Output IP3 (dBm)	NF (dB)	Current (mA)	Gain (d.B)	PlaB (dBm)	Output IP3 (dBm)	NF (dB)
RF Amplifier	13	21,	41\	3/2	/140	101	21.0	41.0	3.2
RF Filter	-2	/	\ <del>-</del> -\	2.0	/ /	S	19.0	39.0	3.3
LO Amp / MMIC Mixer	-9	9	<b>2</b> 23	9.8	80	(S)	6.5	22.2	4.5
IF Amplifier	19	23>	41	2.1	1400	(VXV)	21.0	38.1	5.0
CV111-1	Cumulative Performance			360	21	21.0	38.1	5.0	



Printed Circuit Board Material: .014" FR-4, 4 layers, .062" total thickness



CV111-2: The application circuit can be broken up into four main functions as denoted in the colored dotted areas above: RF/IF diplexing (purple; this is only used with the cellular-band CV products), amplifier matching (green the fing (red), and dc biasing (blue). There are various placeholders for chip components in the circuit schematic so that a common PCB can be used for all WJ single-branch converters. Additional placeholders for other optional functions such as filtering are used included.

RF / IF Amplifier (C12) for optimal gain and input return loss performance. The RF amplifier requires matching elements to optimize the performance of the amplifier to the desired IF center frequency. Since IB bandwidths are typically on the order of 5 to 10%, a simple two element matching network, in the form of either a high-pass of low-pass filter structure, is sufficient to match the MMI Amplifier over these narrow bandwidths. Proper component values for other IF center frequencies can be provided by emailing to applications.engineering@wj.com.

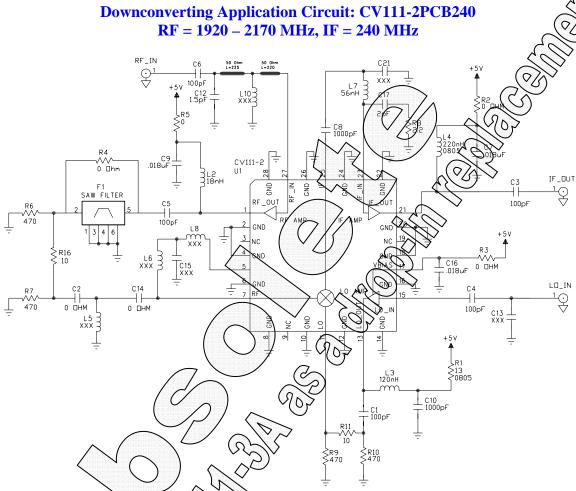
Cacheve the best noise figure performance with the downconverter. The bandpass filter, implemented with a SAW filter on the

application circuit, allows for the suppression of noise from the image frequency. It is permissible to not use a filter and use a 2 dB pad with R6, R7, and R16 instead with slightly degraded noise figure performance.

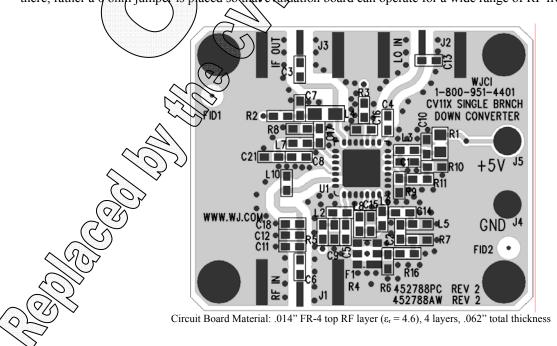
**External Diplexer:** This is only used with the cellular-band CV products. The mixer performs the diplexing internally for the CV111-2; therefore the components shown in the diplexer section should be loaded as follows:  $C2 = C14 = 0 \Omega$ .

**DC** biasing: DC bias must be provided for the RF, LO and IF amplifiers in the converter. R1 sets the operating current for the last stage of the LO amplifier and is chosen to optimize the mixer LO drive level. Proper RF chokes and bypass capacitors are chosen for proper amplifier biasing at the intended frequency of operation. The "+5 V" dc bias should be supplied directly from a voltage regulator.

**Product Information** 



A SAW filter is required in the circuit after the RF Amplifier port of the converter to reduce the image noise into the mixer and be able to properly measure the noise figure of the converter. The WJ evaluation board is not shipped with the SAW filter on there; rather a 0 ohm jumper is placed so that evaluation board can operate for a wide range of RF frequencies.



Product Information

#### CV111-2 Mechanical Information

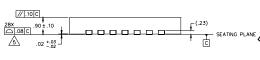
This package may contain lead-bearing materials. The plating material on the pins is PbSn.

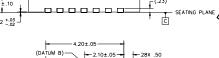
### **Outline Drawing**

# 2X .10 C TERMINAL # <u>6</u> 2X 🛆 .10 C // .10 C

- EXCEPT WHERE NOTED, THIS PART OUTLINE CONFORMS TO JEDEC STANDARD MO-220, ISSUE E (VARIATION VJUC) FOR THERMALLY ENHANCED PLASTIC VERY THIN FINE PITCH QUAD FLAT NO LEAD PACKAGE (QFN).

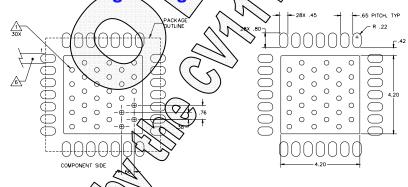
- COPLANARITY APPLIES TO THE EXPOSED GROUND/TI PAD AS WELL AS THE TERMINALS.
- ALPHA-NUMERIC LOT CODE

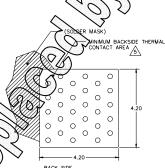






# and Pattern





 $\triangle$ 

NOTES:

- GROUND/THERMAL WAS ARE CRITICAL FOR THE PROPER PERFORMANCE OF THIS DEVICE. WAS SHOULD USE A .35mm (#80/.0135") DIAMETER DRILL AND HAVE A FINAL, PLATED THRU DIAMETER OF .25mm (.010").
- ADD AS MUCH COPPER AS POSSIBLE TO INNER AND OUTER LAYERS NEAR THE PART TO ENSURE OPTIMAL THERMAL PERFORMANCE.
- TO ENSURE RELIABLE OPERATION, DEVICE GROUND PADDLE-TO-GROUND PAD SOLDER JOINT IS CRITICAL.
- ADD MOUNTING SCREWS NEAR THE PART TO FASTEN THE BOARD TO A HEATSINK. ENSURE THAT THE GROUND/THERMAL VIA REGION CONTACTS THE HEATSINK

DO NOT PUT SOLDER MASK ON THE BACK SIDE OF THE PC BOARD IN THE REGION WHERE THE BOARD CONTACTS THE HEATSINK.

- USE 1 OZ. COPPER MINIMUM.
- ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.

### **Product Marking**

The component will be lasermarked with a 11)-2" product label with an alphanumeric ode on the top surface of the package.

cifications for this part will be Tocated website in the "Application Notes" (coigh

### **MSL** Information

Caution! ESD sensitive device.

D Rating: Class 1B

Passes  $\geq 500 \text{V}$  to  $\leq 1000 \text{V}$ Value: Human Body Model (HBM) Test: JEDEC Standard JESD22-A114 Standard:

ESD Rating: Class III

Passes  $\geq 500 \text{V}$  to  $\leq 1000 \text{V}$ Value: Test: Charged Device Model (CDM) Standard: JEDEC Standard JESD22-C101

MSL Rating: Level 1 at +250°C convection reflow JEDEC Standard J-STD-020

### **Functional Pin Layout**

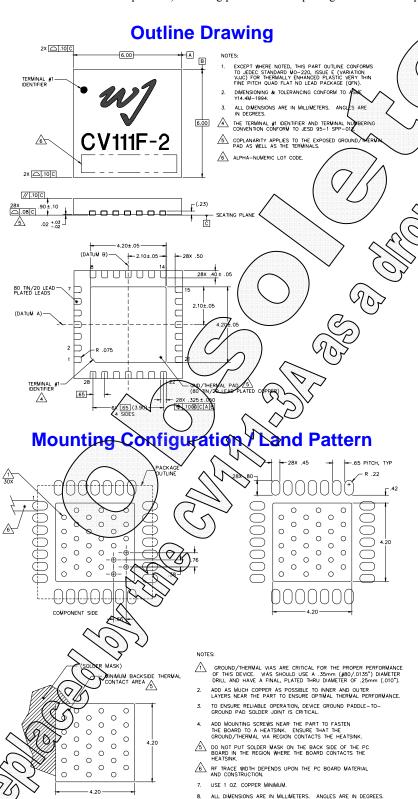
Pin	FUNCTION	Pin	FUNCTION
1	RF Amp	15	LO Amp
1	Output	13	Input
2	GND	16	GND
3	N/C	17	LO Amp Bias
4	GND	18	GND
5	N/C	19	N/C
6	GND	20	GND
7	Mixer RF	21	IF Amp
/	Input	21	Output/Bias
8	GND	22	GND
9	N/C 23		IF Amp
7		23	Input
10	GND	24	GND
11	Mixer LO		Mixer IF
11	Input	25	Output
12	GND	26	GND
13	LO Amp	27	RF Amp
13	Output	21	Input
14	GND	28	GND

Specifications and information are subject to change without notice



### **CV111-2F Mechanical Information**

This package is lead-free/RoHS-compliant. It is compatible with both lead-free (maximum 260°C reflow temperature) and leaded maximum 245°C reflow temperature) soldering processes. The plating material on the pins is annealed matte tin over copped.



# Product Warking

The component with he lasermarked with a "CV111F-2" problem label with an alpharumeric to code on the top surface of the package.

Tape and rect specifications for this part will be located on the website in the "Application Notes" section.

### ESD / MSL Information

Caution! ESD sensitive device.

ESD Rating: Class 1B

Value: Passes ≥ 500V to <1000V
Test: Human Body Model (HBM)
Standard: JEDEC Standard JESD22-A114

ESD Rating: Class III

Value: Passes ≥ 500V to <1000V
Test: Charged Device Model (CDM)
Standard: JEDEC Standard JESD22-C101

MSL Rating: Level 2 at +260°C convection reflow Standard: JEDEC Standard J-STD-020

### **Functional Pin Layout**

Pin	FUNCTION	Pin	FUNCTION
1	RF Amp	15	LO Amp
1	Output	13	Input
2	GND	16	GND
3	N/C	17	LO Amp Bias
4	GND	18	GND
5	N/C	19	N/C
6	GND	20	GND
7	Mixer RF	21	IF Amp
,	Input	21	Output/Bias
8	GND	22	GND
9	N/C	23	IF Amp
9		23	Input
10	GND	24	GND
11	Mixer LO	25	Mixer IF
	Input	23	Output
12	GND	26	GND
13	LO Amp	27	RF Amp
13	Output	21	Input
14	GND	28	GND

Specifications and information are subject to change without notice

BACK SIDE